Cross-Section View VS1003B
49pin FBGA (RoHS) Package

Substrate
- plate composition: Cu, Au and Ni
- plate thickness: Cu = 22.5 +/- 7.5 microns
  Au = 0.5 to 1.2 microns
  Ni = 5.0 microns minimum
- Total substrate thickness: 0.3MM +/- 0.04 MM

Material
- Solderball: Sn 96.5%, Ag 3%, Cu 0.5%
- Substrate: HL832NX, AUS 308
- Epoxy Die Attach: ABLEBOND 2000B
- Bonding Wire: 25 um
- Mold Compound: EMEG760V